

SEMICONDUCTOR CHIP HAVING A SUPPORTING MEMBER, TAPE SUBSTRATE,
SEMICONDUCTOR PACKAGE HAVING THE SEMICONDUCTOR CHIP AND THE
TAPE SUBSTRATE, AND THE METHOD OF MANUFACTURING THE SAME

THIS APPLICATION IS A DIVISIONAL OF
APPLICATION 10/197,529

TTN
9/1/04

5 CROSS-REFERENCE TO RELATED APPLICATION

This application claims the priority benefit of Japanese Patent Application No.
2001-219182, filed July 19, 2001, the entire disclosure of which is incorporated herein
by reference.

10 BACKGROUND OF THE INVENTION

1. Field of the invention

The invention relates to a semiconductor chip, more particularly to a
semiconductor chip having a support member. The invention further relates to a
tape substrate, more particularly to a tape substrate having a support member.

15 Moreover, the invention relates to a semiconductor package having the
semiconductor chip and the tape substrate. Furthermore, the invention relates to a
method of manufacturing the semiconductor chip and the semiconductor package.

2. Description of the related art

20 Referring to Fig. 20, a semiconductor chip 1 of the related arts, which is used
for a semiconductor package, includes a single supporting member 4, pads 2, bump
electrodes 3, each of which is formed on one of the pads 2. The pads 2 are formed